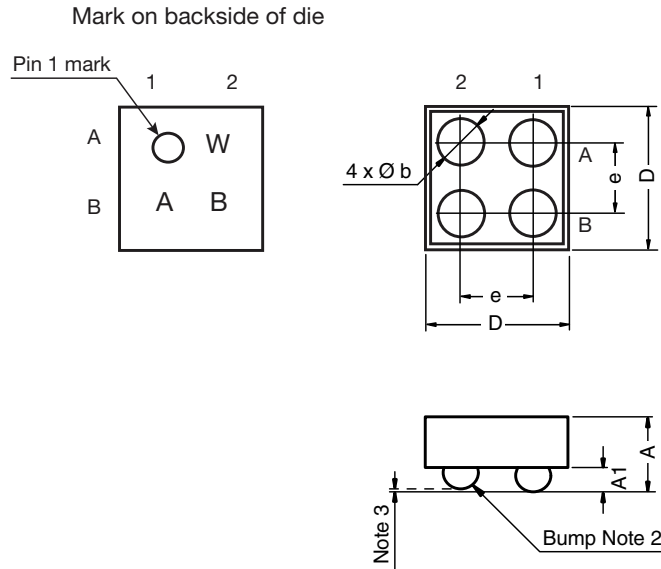


WCSP4: 4 Bumps

(2 x 2 , 0.4 mm pitch, 208 μm bump height, 0.8 mm x 0.8 mm die size)



Notes

- (1) Laser mark on the backside surface of die
- (2) Bumps are SAC396
- (3) 0.050 max. coplanarity

| DIM. | MILLIMETERS ^a | | | INCHES | | |
|------|--------------------------|-------|-------|--------|--------|--------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.515 | 0.530 | 0.545 | 0.0202 | 0.0208 | 0.0214 |
| A1 | 0.208 | | | 0.0081 | | |
| b | 0.250 | 0.260 | 0.270 | 0.0098 | 0.0102 | 0.0106 |
| e | 0.400 | | | 0.0157 | | |
| D | 0.720 | 0.760 | 0.800 | 0.0182 | 0.0193 | 0.0203 |

Note

a. Use millimeters as the primary measurement.

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